

# THERM-A-FORM™ CIP35

## Thermally Conductive Cure-in-place Compound

### Customer Value Proposition:

THERM-A-FORM™ thermally conductive silicone elastomer products are dispensable form-in-place compounds designed for heat transfer without excessive compressive force in electronics cooling applications. These versatile liquid reactive materials can be dispensed and then cured into complex geometries for cooling of multi-height components on a PCB without the expense of a molded sheet. Each compound is available in ready-to-use cartridge systems, eliminating weighing, mixing, and degassing procedures.



### Features and Benefits:

- Dispensable form-in-place gap filling, potting, sealing, and encapsulating
- Excellent blend of high thermal conductivity, flexibility, and ease of use
- Conformable to irregular shapes without excessive force on components
- Ready-to-use cartridge system eliminates weighing, mixing, and de-gassing steps
- Variety of kit sizes and configurations available to suit any application (handheld twin-barrel cartridges, Semco® tubes, and pneumatic applicators)
- Vibration damping
- Long shelf life, no settling or degradation of cure
- Sag resistance. Maintains shape during cure

### Contact Information:

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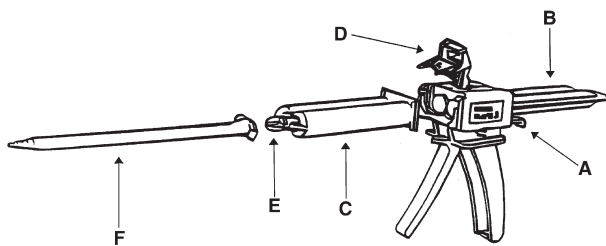
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**THERM-A-FORM CIP35 - Product Information**

THERM-A-FORM CIP35 Thermally Conductive Pads			
Typical Properties		CIP35	Test Method
Physical	Color	Green	--
	Binder	Silicone	--
	Filler	Aluminum Oxide / Boron Nitride	---
	Number of Components	2 part	---
	Mix Ratio	1 : 1	---
	Specific Gravity	2.87	ASTM D792
	Hardness, Shore A	55	ASTM D2240
	Viscosity, poise	5000	Mod. ASTM D2196
	Pot Life, minutes	100	Time to 2X starting viscosity at 23°C
	Cure Cycles - for set up	30 min @ 150°C 180 min @ 100°C 48 hrs @ 23°C	Chomerics
Thermal	Thermal Conductivity, W/m-K	3.5	ASTM D5470
	Operating Temperature Range, °F [°C]	-67 to 392 [-55 to 200]	ASTM D5470
Electrical	Dielectric Strength, Kvac/mm (Vac/mil)	10 (250)	ASTM D149
	Volume Resistivity, ohm-cm	1.0 x 10 <sup>14</sup>	ASTM D257
Regulatory	RoHS Compliant	Yes	Chomerics
	Outgassing, %TML [%CVCM]	0.22 [0.06]	ASTM E595
	Flammability Rating (file E140244)	UL94-V0	UL 94
	Shelf Life	12 months	Chomerics

**Ordering Information**



Part Number	Volume (mass)	Description
65-00-CIP35-0045	45 cc	1:1 Dual element Cartridge
65-00-CIP35-0200	200 cc	
65-00-CIP35-0400	400 cc	

Figure 1: Typical Applicator

Mixpac® Dispensing Systems are available from multiple sources. When contacting Mixpac® equipment suppliers, reference cartridge volume (cc) and dual element cartridge A:B mix ratio. Refer to table for volume and mix ratio information.

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